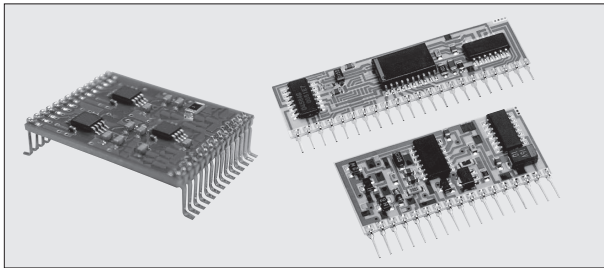


KA Custom Hybrid IC



■ Features

- Adjustment processes are decreased by function and ratio trimmings.
- Various types of package are available.
- High reliability achieved by KOA's original thick film technology.

■ EU-RoHS requirements

- Each constructional element of thick film printed circuit substrate and printed board has optimized material. Inner connecting solder is lead-free.

■ Applications

- Automotives applications (ECU, Power Windows)
- Power supply devices (DC/DC converters, AC/DC converters, Stabilizer, Lithium ion battery charger circuit)
- Industry devices (control circuits)
- Telecommunication equipment (Telephone switchboard, LAN, Transceivers, VCO, VTXO)

■ Component

KA Series			
	Item	Printing	Mounting
Substrate materials	Alumina	○	○
	Glass epoxy	×	○
Conductors · Resistors	Item	Ag-Pd	Ag-Pt
	Conductor resistance	18mΩ/□/15μm	5mΩ/□/10μm
	Heat shock	-55°C~+125°C 300 Cycles	-55°C~+125°C 500 Cycles
	Printed Resistor	5Ω~10MΩ ±100×10 ⁻⁶ /K	
Mounting	Item	Specifications	
	BGA	0.5mm Pitch~	
	QFP	0.4mm Pitch~	
	Chip	0.4mm×0.2mm~	
Package · Outside terminals	Package	Lead pitch	
	SIP	1.8mm, 2.0mm, 2.5mm, 2.54mm	
	DIP, SOP	1.27mm, 1.8mm, 2.54mm	
	ZIP	2.54mm	
	BGA, LGA	1.0mm~	
Overcoating · Plating	Over Coating	Color	UL Standard
	Epoxy metamorphic phenol	Black	94 V-0 approved
	Epoxy	Black	94 V-1 approved

Thick film printed circuit board is also available.

■ Type Designation

Example

